

# 1.5V Drive Pch+Pch MOSFET

## TT8J1

### ●Structure

Silicon P-channel MOSFET

### ●Features

- 1) Low On-resistance.
- 2) High Power Package.
- 3) Low voltage drive. (1.5V)

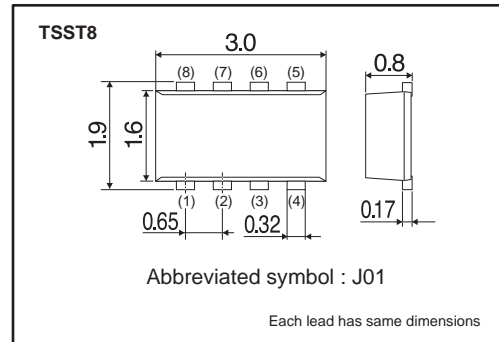
### ●Applications

Switching

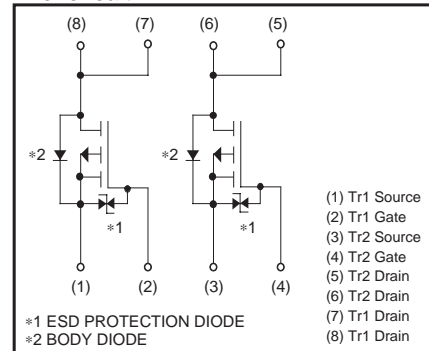
### ●Packaging specifications

Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
TT8J1		○

### ●Dimensions (Unit : mm)



### ●Inner circuit



### ●Absolute maximum ratings (Ta=25°C)

<It is the same ratings for the Tr1 and Tr2.>

Parameter	Symbol	Limits	Unit	
Drain-source voltage	$V_{DS}$	-12	V	
Gate-source voltage	$V_{GS}$	±10	V	
Drain current	Continuous	$I_D$	±2.5	A
	Pulsed	$I_{DP}$ *1	±10	A
Source current (Body diode)	Continuous	$I_S$	-0.8	A
	Pulsed	$I_{SP}$ *1	-10	A
Total power dissipation	$P_D$ *2	1.25	W / TOTAL	
		1.0	W / ELEMENT	
Channel temperature	$T_{ch}$	150	°C	
Range of Storage temperature	$T_{stg}$	-55 to +150	°C	

\*1  $P_{ws} \leq 10 \mu s$ , Duty cycles  $\leq 1\%$

\*2 Mounted on a ceramic board

### ●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	$R_{th(ch-a)}$ *	100	°C / W / TOTAL
		125	°C / W / ELEMENT

\* Mounted on a ceramic board

### ●Electrical characteristics (Ta=25°C)

<It is the same characteristics for the Tr1 and Tr2.>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	-	-	$\pm 10$	$\mu A$	$V_{GS}=\pm 10V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	-12	-	-	V	$I_D = -1mA, V_{GS}=0V$
Zero gate voltage drain current	$I_{DSS}$	-	-	-1	$\mu A$	$V_{DS} = -12V, V_{GS}=0V$
Gate threshold voltage	$V_{GS(th)}$	-0.3	-	-1.0	V	$V_{DS} = -6V, I_D = -1mA$
Static drain-source on-state resistance	$R_{DS(on)}$ *	-	44	61	m $\Omega$	$I_D = -2.5A, V_{GS} = -4.5V$
		-	60	84	m $\Omega$	$I_D = -1.2A, V_{GS} = -2.5V$
		-	81	121	m $\Omega$	$I_D = -1.2A, V_{GS} = -1.8V$
		-	110	220	m $\Omega$	$I_D = -0.5A, V_{GS} = -1.5V$
Forward transfer admittance	$ Y_{fs} $ *	3.5	-	-	S	$V_{DS} = -6V, I_D = -2.5A$
Input capacitance	$C_{iss}$	-	1350	-	pF	$V_{DS} = -6V$
Output capacitance	$C_{oss}$	-	130	-	pF	$V_{GS}=0V$
Reverse transfer capacitance	$C_{rss}$	-	125	-	pF	$f=1MHz$
Turn-on delay time	$t_{d(on)}$ *	-	9	-	ns	$V_{DD} \hat{=} -6V$
Rise time	$t_r$ *	-	35	-	ns	$V_{GS} = -4.5V$
Turn-off delay time	$t_{d(off)}$ *	-	130	-	ns	$I_D = -1.2A$
Fall time	$t_f$ *	-	85	-	ns	$R_L \hat{=} 5\Omega$
Total gate charge	$Q_g$ *	-	13	-	nC	$V_{DD} \hat{=} -6V$
Gate-source charge	$Q_{gs}$ *	-	2.5	-	nC	$V_{GS} = -4.5V$
Gate-drain charge	$Q_{gd}$ *	-	2.0	-	nC	$I_D = -2.5A$ $R_L \hat{=} 2.4\Omega / R_G = 10\Omega$

\* Pulsed

### ●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	$V_{SD}$ *	-	-	-1.2	V	$I_S = -2.5A, V_{GS}=0V$

\* Pulsed

●Electrical characteristic curves

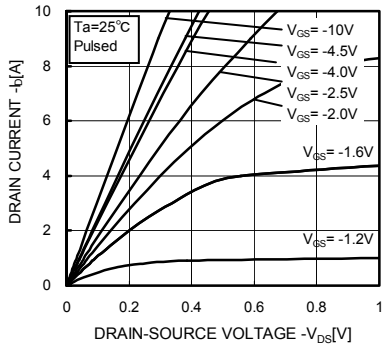


Fig.1 Typical Output Characteristics( I )

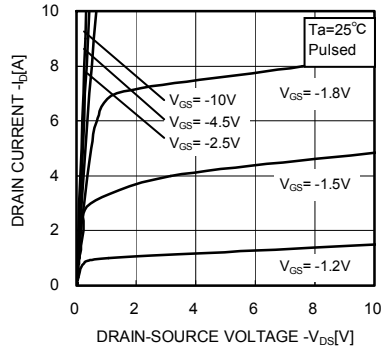


Fig.2 Typical Output Characteristics( II )

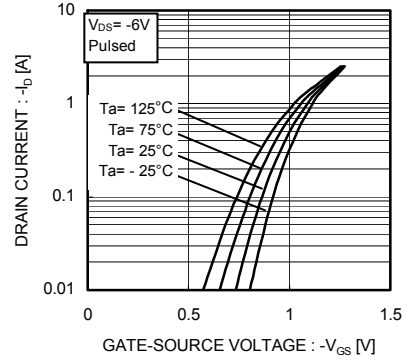


Fig.3 Typical Transfer Characteristics

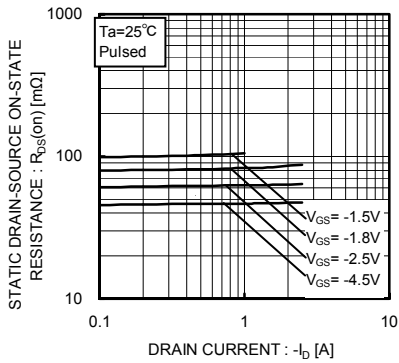


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

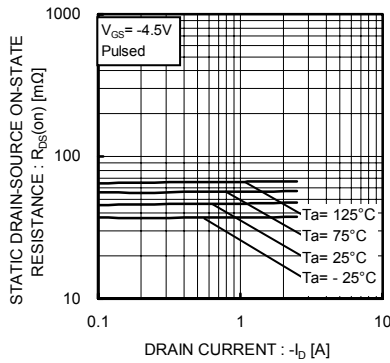


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

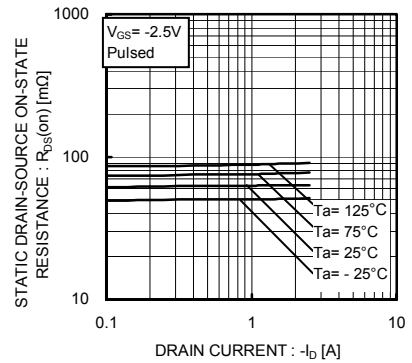


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( III )

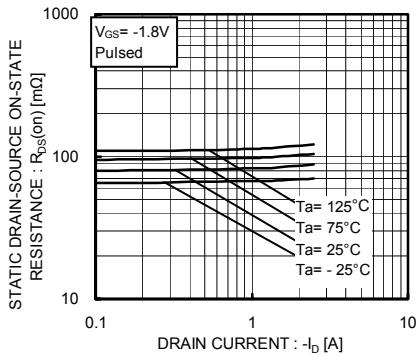


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current( IV )

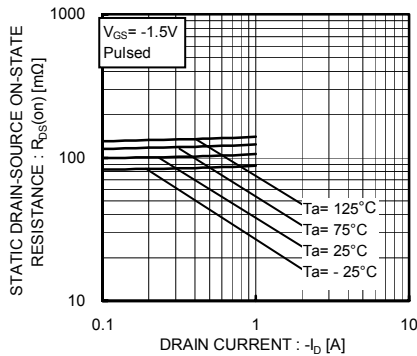


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current( V )

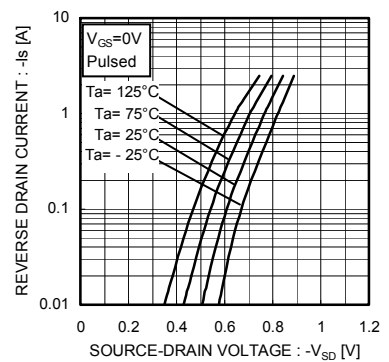


Fig.9 Reverse Drain Current vs. Source-Drain Voltage

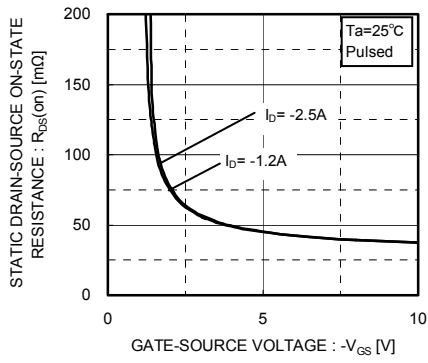


Fig.10 Static Drain-Source On-State Resistance vs. Gate Source Voltage

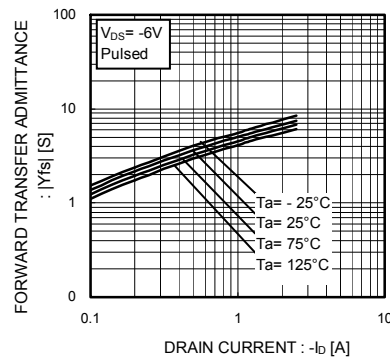


Fig.11 Forward Transfer Admittance vs. Drain Current

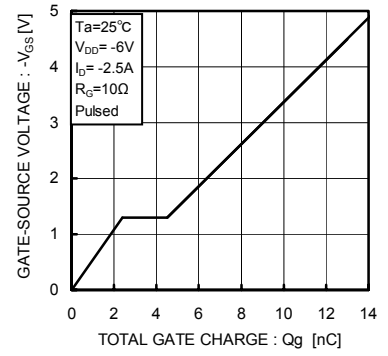


Fig.12 Dynamic Input Characteristics

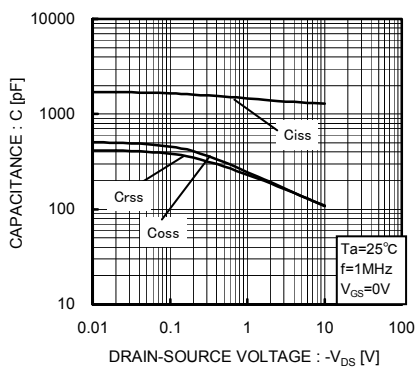


Fig.13 Typical Capacitance vs. Drain-Source Voltage

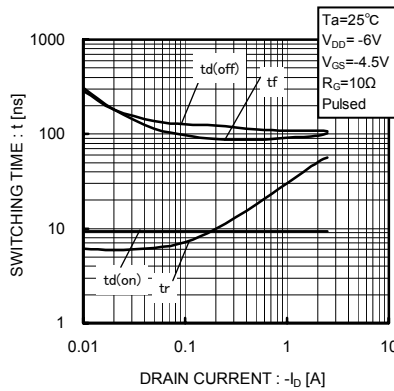


Fig.14 Switching Characteristics

●Measurement circuits

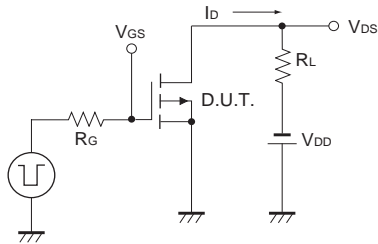


Fig.1-1 Switching Time Measurement Circuit

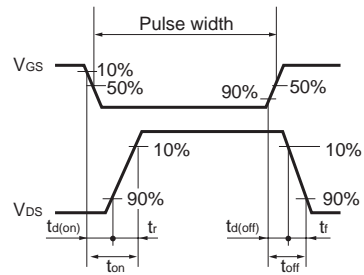


Fig.1-2 Switching Waveforms

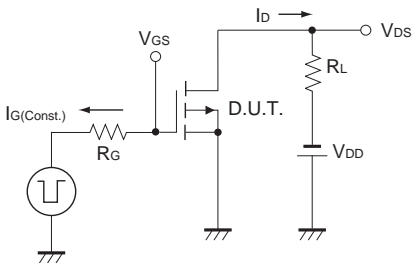


Fig.2-1 Gate Charge Measurement Circuit

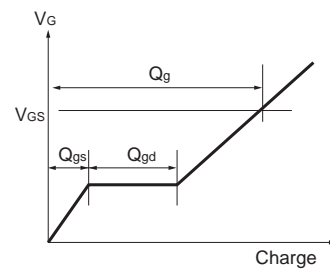


Fig.2-2 Gate Charge Waveform

●Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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